

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Customer Number: 89518
 :
 Mou-Shiung Lin et al. : Confirmation Number: 6103
 :
 Application No.: 10/055,560 : Group Art Unit: 2813
 :
 Filed: January 22, 2002 : Examiner: Mitchell, James M.
 :

For: INTEGRATED CHIP PACKAGE STRUCTURE USING METAL SUBSTRATE AND METHOD OF
 MANUFACTURING THE SAME

Mail Stop AMENDMENT
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

CERTIFICATE OF ELECTRONIC TRANSMISSION

I hereby certify that this correspondence is being electronically-transmitted to the
 United States Patent and Trademark Office on September 24, 2009.
 /Tobi Terry/

 Tobi Terry

Dear Sir:

Transmitted herewith is a Response to Notification of Non-Compliant Amendment in the above-identified application.

- ☒ No additional fee is required.
☐ Applicant is entitled to small entity status under 37 CFR 1.27

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	49	138	0	\$52.00 =	\$0.00
Independent Claims	3	4	0	\$220.00 =	\$0.00
Multiple dependent claims newly presented					\$0.00
Fee for extension of time					\$0.00
					\$0.00
Total of Above Calculations					\$0.00

- ☒ The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 502624, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

McDERMOTT WILL & EMERY LLP

/Dennis A. Duchene/

Dennis A. Duchene
 Registration No. 40,595

11682 El Camino Real, Suite 400
 San Diego, CA 92130
 Phone: 858.720.3300 DAD:tt
 Facsimile: 858.720.7800
Date: September 24, 2009

**Please recognize our Customer No. 89518 as our
 correspondence address.**